



UNITED STATES PATENT AND TRADEMARK OFFICE

#9/Amend A
9.30.01
C. Wills

In re application of:

WARREN M. FARNWORTH
SALMAN AKRAM

Serial No. 09/266,237

Art Unit: 2858

Filing Date: March 10, 1999

Examiner: KORBERT, R.

For: TEST INTERCONNECT FOR BUMPED
SEMICONDUCTOR COMPONENTS AND
METHOD OF FABRICATION

Attorney Docket No. 97-1433

RECEIVED
SEP 28 2001
TECHNOLOGY CENTER 2800

AMENDMENT

September 17, 2001

Assistant Commissioner of Patents
BOX AMENDMENT (FEE)
Washington D.C. 20231

Sir:

This Amendment is in response to the Office Action dated June 18, 2001 having a statutory period for response set to expire on September 18, 2001. Please amend the captioned case as follows.

In the Specification

On page 6, lines 27-30, please substitute the following clean replacement paragraph:

A1
--Figures 2C and 2D are schematic cross sectional views of the interconnect contact of Figure 2B electrically engaging a bumped contact on a component;--

On page 24, lines 21-34 please substitute the following clean replacement paragraph:

A2
--The interconnect 10A also include terminal contacts 84 attached to the contact pads 38D. The terminal contacts 84 comprise metal balls soldered, or otherwise bonded, to the